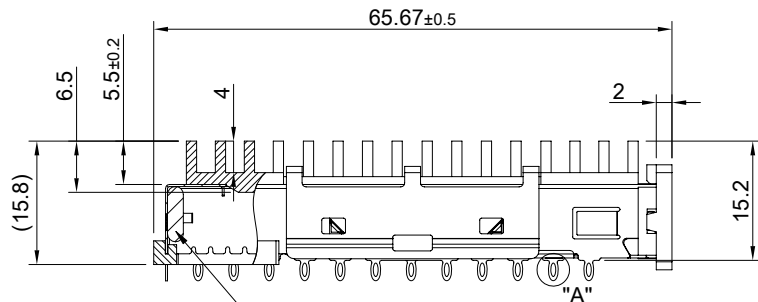
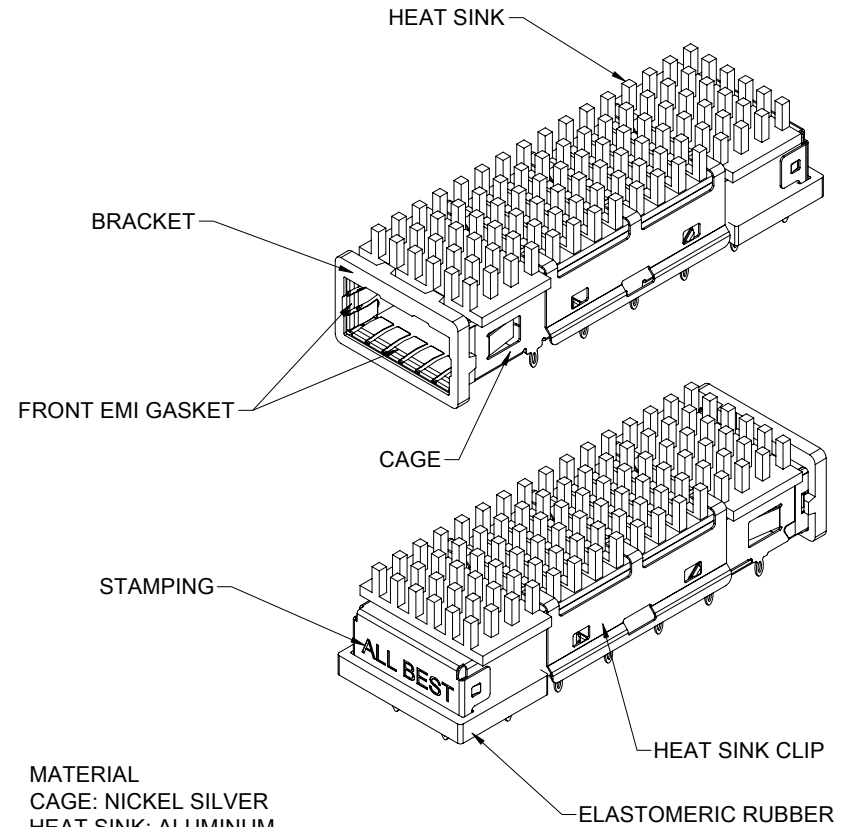
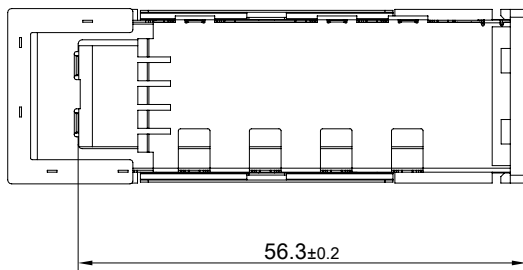
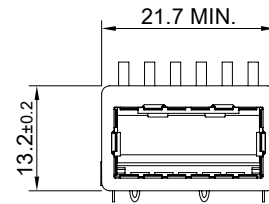


DETAIL A
SCALE 5:1



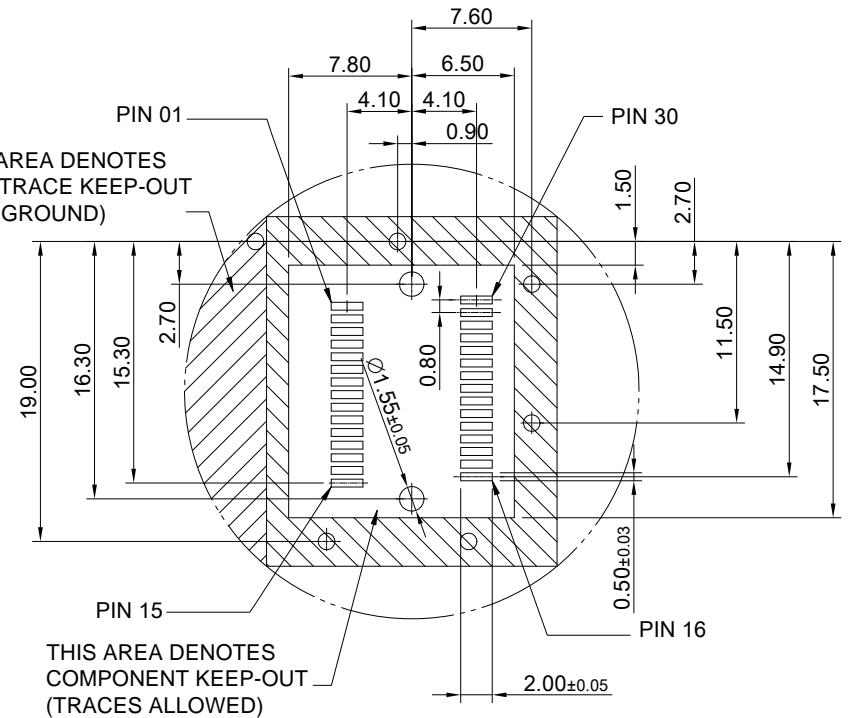
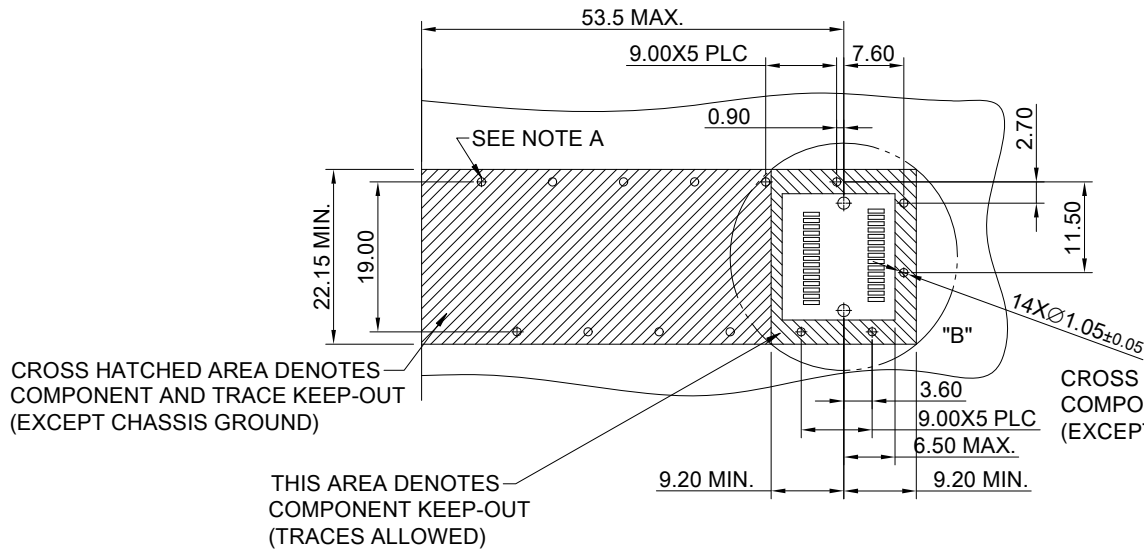
REAR EMI GASKET



MATERIAL
 CAGE: NICKEL SILVER
 HEAT SINK: ALUMINUM
 HEAT SINK CLIP: STAINLESS STEEL
 FRONT EMI GASKET: COPPER ALLOY
 REAR EMI GASKET: CONDUCTIVE FOAM
 ELASTOMERIC RUBBER: CONDUCTIVE RUBBER
 BRACKET: ZINC ALLOY

FINISH
 HEAT SINK: ANODE PROCESS
 FRONT EMI GASKET: TIN OVER COPPER
 BRACKET: TIN

	TITLE: XFP Cage Assembly With Heat Sink 6.5mm Tall		SHEET: 1/2	REV. I
	DWG#: R-CG-008030-11		CHECKED: Gary Kang	
	UNIT: mm	SCALE: A4 1:1	MATERIAL: RoHS Compliant	
	TOLERANCE: Angle: ± 1° X ± 0.25 .X ± 0.2 .XX ± 0.15		DRAWN: Yilu	APPROVED: George Yang
		DATE: 09/10/2019		

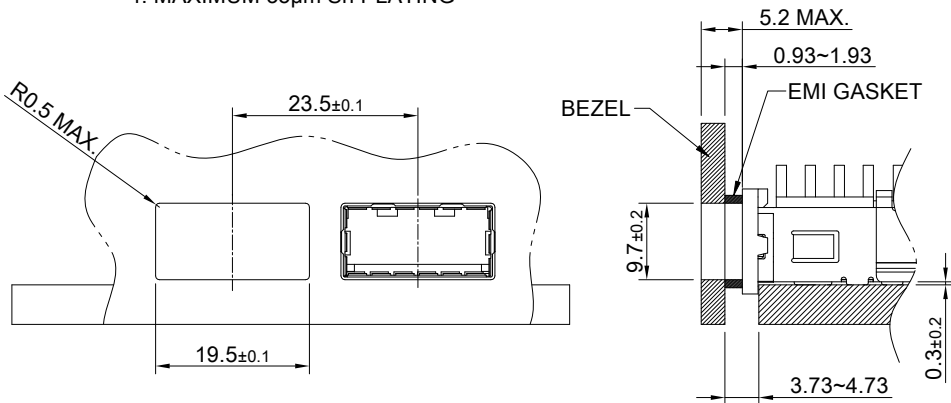




DETAILED HOST BOARD MECHANICAL LAYOUT
TOLERANCE: ±0.05

DETAILED HOST BOARD MECHANICAL LAYOUT
TOLERANCE: ±0.05

DETAIL B
SCALE 2:1

- NOTE A: RECOMMENDATION FOR P.C.B. HOLES
1. HOLE Ø AFTER DRILLING: 1.15 ± 0.02
 2. HOLE Ø AFTER TIN LEAD PLATED: 1.05 ± 0.05
 3. 25µm-50µm COPPER UNDERPLATED
 4. MAXIMUM 35µm Sn PLATING



 ALL BEST ELECTRONICS CO., LTD.	TITLE: XFP Cage Assembly With Heat Sink 6.5mm Tall		SHEET: 2/2	REV. I
	DWG#: R-CG-008030-11		CHECKED: Gary Kang	
UNIT: mm	SCALE: A4 1:1	FINISH:	APPROVED: George Yang	
 THIRD ANGLE PROJECTION		MATERIAL: RoHS Compliant	DATE: 09/10/2019	
TOLERANCE: Angle: ± 1° X ± 0.15 .X ± 0.1 .XX ± 0.05		DRAWN: Yilu		